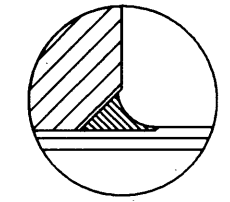
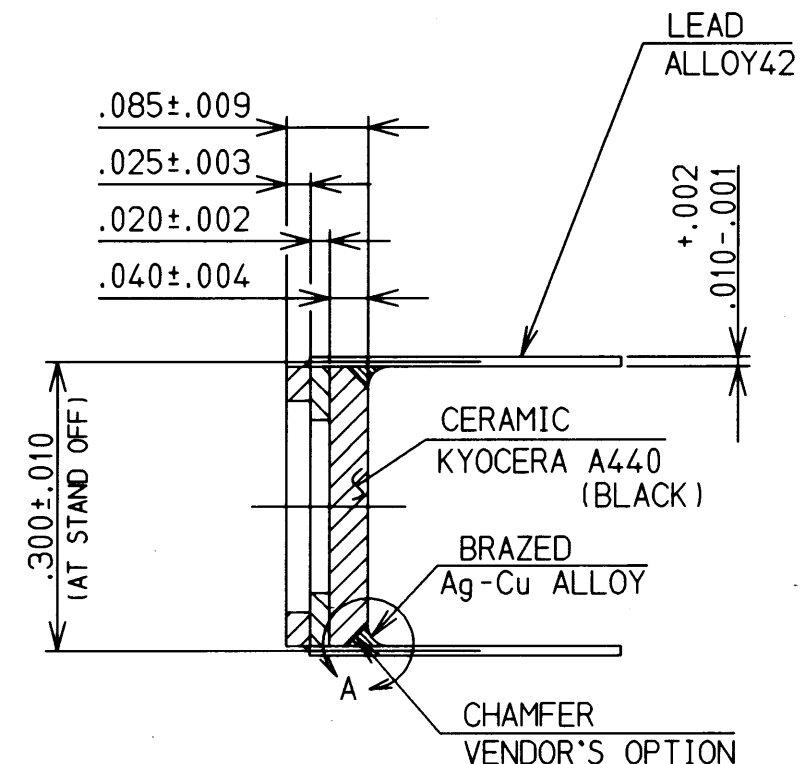
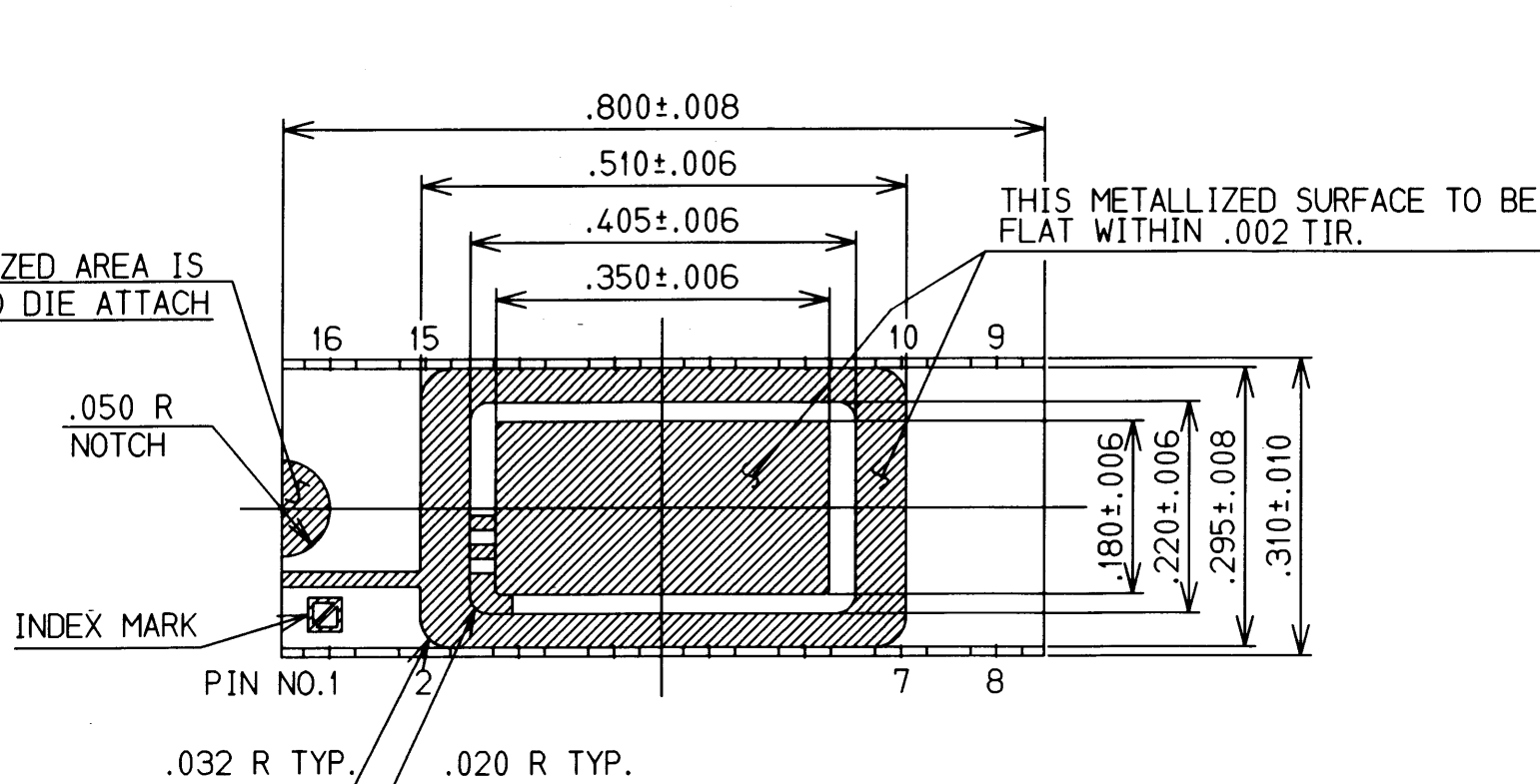
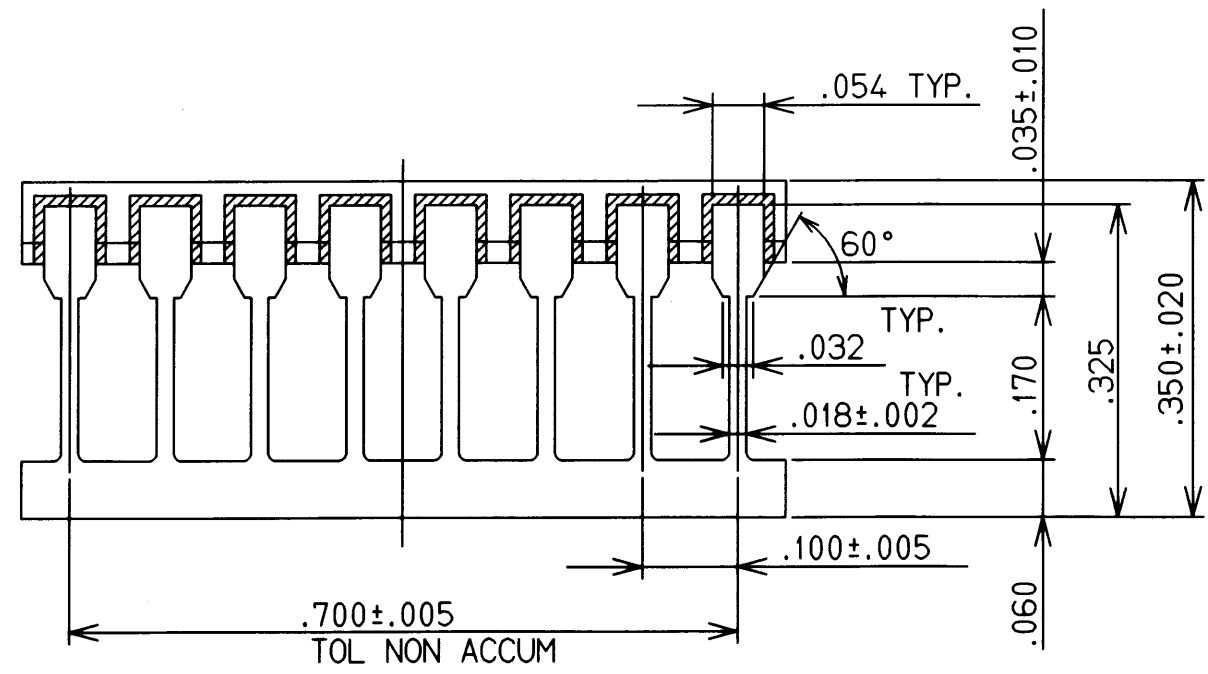


THIS METALLIZED AREA IS CONNECTED TO DIE ATTACH PAD



DETAIL-A



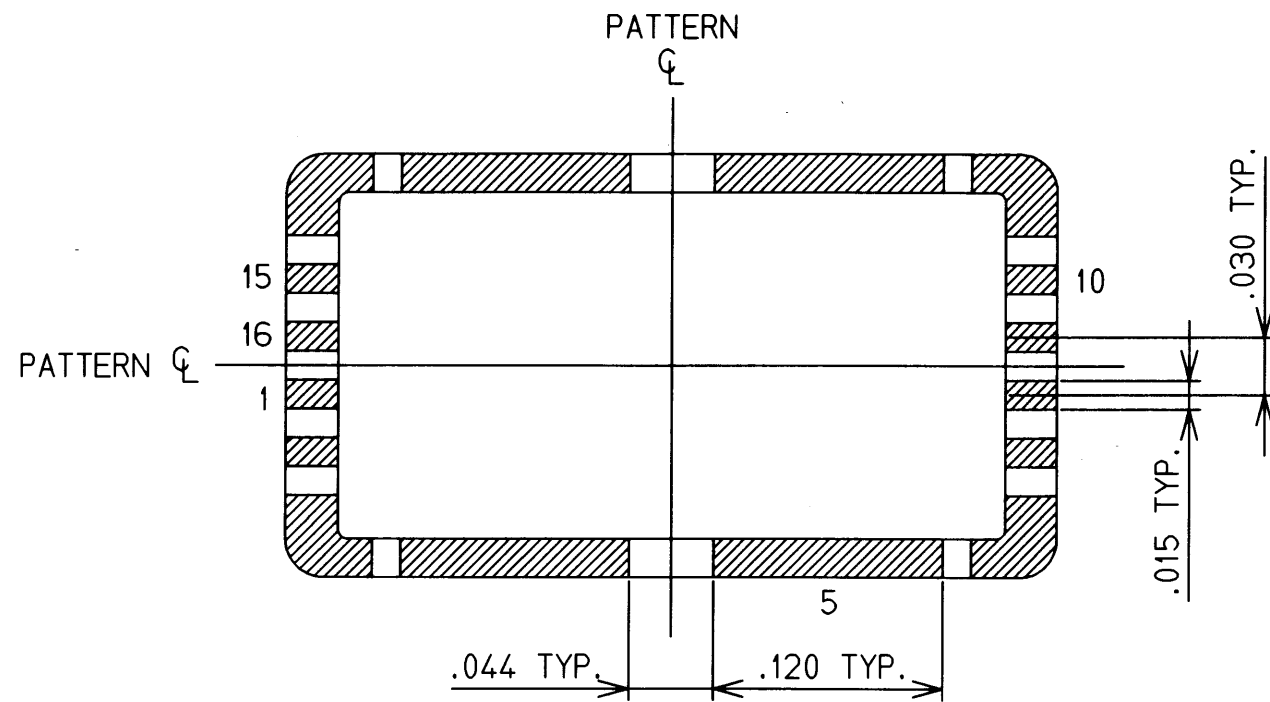
NOTES

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
5. LEAD RESISTANCE :0.20Ω MAX.

MODIFICATION						NAME 16 LEAD SIDE BRAZED PACKAGE	TOLERANCE UNLESS OTHERWISE SPECIFIED ±.005	DRAWN M.K	CHECKED A.F/T.A	APPROVED K.M	DATE JUL.30.'92
						SCALE 5/1	MATERIAL AS INDICATED				
						KYOCERA	KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO. KD-81086-B		SHEET 1/2	

SB016L086-1		S=0	D=0
DRAWN	CHECKED	APPROVED	DATE
M.K	A.F/T.A	K.M	JUL.30.'92
DRAWING NO. KD-81086-B		SHEET 1/2	

B	REDRAWN (CONVERTED CAD DATA)	JUL.8.'98	M. SU	SH.K/S.F	T. A
	CHANGED	DATE	DRAWN	CHECKED	APPROVED



BONDING PATTERN

MODIFICATION						NAME 16 LEAD SIDE BRAZED PACKAGE	TOLERANCE UNLESS OTHERWISE SPECIFIED	DRAWN M. SU	CHECKED SH.K/S.F	APPROVED T. A	DATE JUL.8.'98
						SCALE 10/1	MATERIAL	<i>M. Suwa</i>	<i>Shige R. S. Kubo</i>	<i>T. Atsu</i>	
	<b>B</b>	ADDED: THIS SHEET (2/2) CHANGED	JUL.8.'98	M. SU	SH.K/S.F	T. A		KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO. KD-81086-B		SHEET 2/2
		DATE	DRAWN	CHECKED	APPROVED						